

## CSD17303Q5-VB Datasheet N-Channel 30 V (D-S) MOSFET

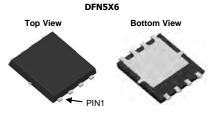
PRODUCT SUMMARY					
V <sub>DS</sub> (V)	R <sub>DS(on)</sub> (Ω)	I <sub>D</sub> (A) <sup>a, e</sup>	Q <sub>g</sub> (Typ.)		
30	0.0018 at V <sub>GS</sub> = 10 V	160	82 nC		
	0.0025 at V <sub>GS</sub> = 4.5 V	130	02 110		

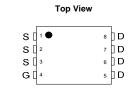
#### **FEATURES**

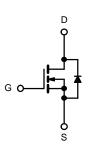
- Trench Power MOSFET
- 100 % R<sub>g</sub> and UIS Tested

#### **APPLICATIONS**

- OR-ing
- Server ٠







RoHS COMPLIANT

N-Channel MOSFET

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V <sub>DS</sub>	30	V	
Gate-Source Voltage	V <sub>GS</sub>	± 20	v	
	T <sub>C</sub> = 25 °C		160 <sup>a, e</sup>	
Continuous Drain Current (T 175 °C)	T <sub>C</sub> = 70 °C		90 <sup>e</sup>	
Continuous Drain Current (T <sub>J</sub> = 175 °C)	T <sub>A</sub> = 25 °C	I I <sub>D</sub>	33 <sup>b, c</sup>	Α
	T <sub>A</sub> = 70 °C		29.8 <sup>b, c</sup>	
Pulsed Drain Current		I <sub>DM</sub>	300	
Avalanche Current Pulse	L = 0.1 mH	I <sub>AS</sub>	36	
Single Pulse Avalanche Energy	L = 0.1 mm	E <sub>AS</sub>	64.8	mJ
Continuous Source-Drain Diode Current	T <sub>C</sub> = 25 °C	I <sub>S</sub>	90 <sup>a, e</sup>	Α
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C		3.13 <sup>b, c</sup>	
Maximum Power Dissipation	T <sub>C</sub> = 25 °C		250 <sup>a</sup>	
	T <sub>C</sub> = 70 °C	P <sub>D</sub>	175	w
	T <sub>A</sub> = 25 °C		3.75 <sup>b, c</sup>	vv
	T <sub>A</sub> = 70 °C		2.63 <sup>b, c</sup>	
Operating Junction and Storage Temperature R	ange	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 175	°C

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient <sup>b, d</sup>	$t \le 10 \text{ s}$	R <sub>thJA</sub>	32	40	°C/W	
Maximum Junction-to-Case	Steady State R <sub>thJC</sub> 0.5 0.6		0/10			

Notes:

a. Based on  $T_C = 25 \text{ °C}$ . b. Surface mounted on 1" x 1" FR4 board.

c. t = 10 s.

d. Maximum under steady state conditions is 90 °C/W.

e. Calculated based on maximum junction temperature. Package limitation current is 90 A.

<b>SPECIFICATIONS</b> (T <sub>J</sub> = 25 °C, unless otherwise noted)								
Parameter	Symbol	Test Conditions	Min .	Тур.	Max.	Unit		
Static								
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 V, I_{D} = 250 \mu A$	30			V		
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I <sub>D</sub> = 250 μA		35		mV/°C		
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	$I_{\rm D} = 250 \mu \text{A}$		- 7.5				
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	1.5		2.5	V		
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			1	μΑ		
		$V_{DS} = 30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 55 \text{ °C}$			10			
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	90			Α		
Drain-Source On-State Resistance <sup>a</sup>	_	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 32 A		0.0018				
	R <sub>DS(on)</sub>	$V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 29 \text{ A}$		0.0025		Ω		
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 32 A		160		S		
Dynamic <sup>b</sup>	•			- <b>I</b>		<b>I</b>		
Input Capacitance	C <sub>iss</sub>				9900	pF		
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 12.5 V, V <sub>GS</sub> = 0 V, f = 1 MHz			1725			
Reverse Transfer Capacitance	C <sub>rss</sub>				970			
Total Gate Charge	Qg	V <sub>DS</sub> = 15 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 32 A			83	nC		
					82			
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS}$ = 15 V, $V_{GS}$ = 4.5 V, $I_{D}$ = 29 A			34			
Gate-Drain Charge	Q <sub>gd</sub>				29			
Gate Resistance	R <sub>g</sub>	f = 1 MHz		1.4	2.1	Ω		
Turn-On Delay Time	t <sub>d(on)</sub>			18	27	ns		
Rise Time	tr	$V_{DD} = 15 \text{ V}, \text{ R}_1 = 0.555 \Omega$		11	17			
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 27 \text{ A}, \text{ V}_{\text{GEN}} = 10 \text{ V}, \text{ R}_g = 1 \Omega$		70	105			
Fall Time	t <sub>f</sub>			10	15			
Turn-On Delay Time	t <sub>d(on)</sub>			55	83			
Rise Time	t <sub>r</sub>	$V_{DD} = 15 \text{ V}, \text{ R}_{1} = 0.625 \Omega$		180	270			
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 24$ A, $V_{GEN}$ = 4.5 V, $R_g$ = 1 $\Omega$		55	83			
Fall Time	t <sub>f</sub>	C C C C C C C C C C C C C C C C C C C		12	18			
Drain-Source Body Diode Characteristic				I				
Continuous Source-Drain Diode Current	۱ <sub>S</sub>	T <sub>C</sub> = 25 °C			100	A		
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>	-		1	200			
Body Diode Voltage	V <sub>SD</sub>	I <sub>S</sub> = 22 A		0.8	1.2	V		
Body Diode Reverse Recovery Time	t <sub>rr</sub>			52	78	ns		
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>			70.2	105	nC		
Reverse Recovery Fall Time	t <sub>a</sub>	$I_F = 20 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}, \text{ T}_J = 25 ^\circ\text{C}$		27				
Reverse Recovery Rise Time	t <sub>b</sub>			25		ns		

Notes:

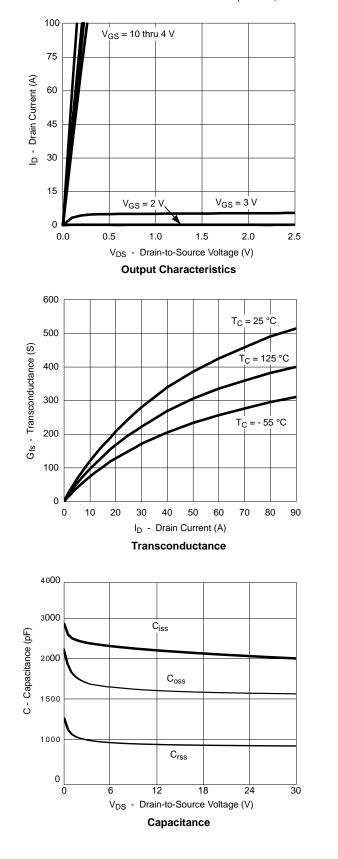
a. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 %.

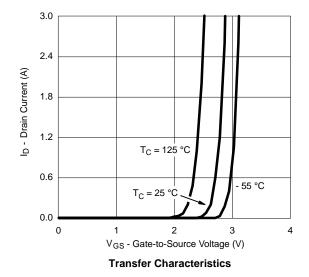
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

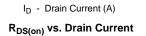
Bsemi

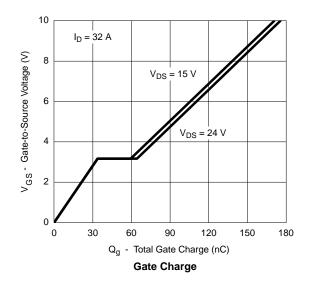
www.VBsemi.com



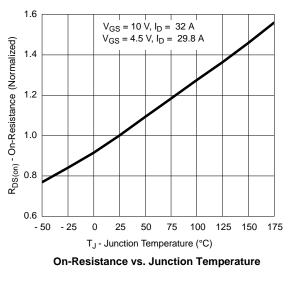


## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

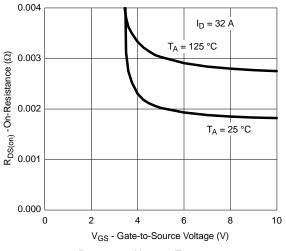




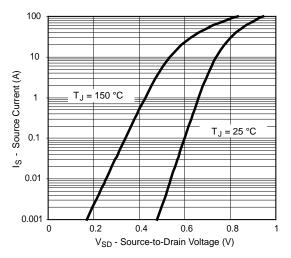




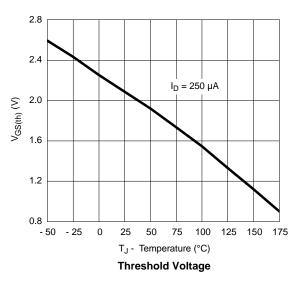
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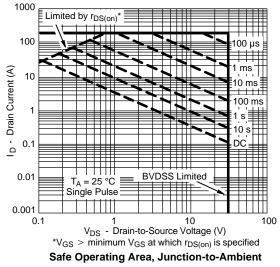


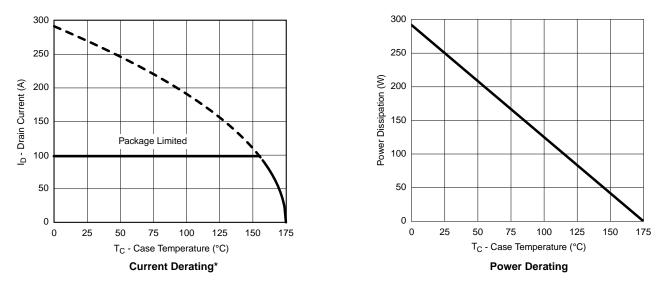
R<sub>DS(on)</sub> vs. V<sub>GS</sub> vs. Temperature



Forward Diode Voltage vs. Temperature

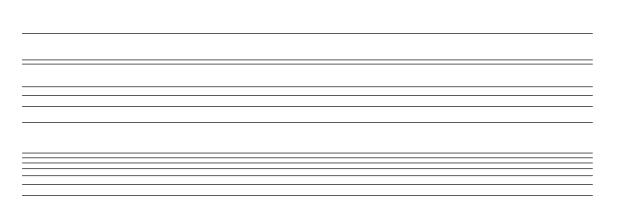




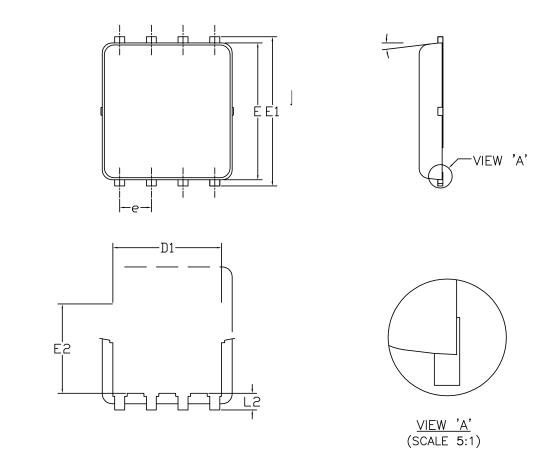


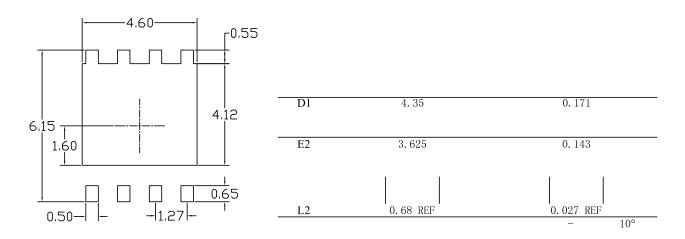
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\* The power dissipation  $P_D$  is based on  $T_{J(max)} = 175 \text{ °C}$ , using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



Normalized Thermal Transient Impedance, Junction-to-Case





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